selectively cut. This eliminates the necessity of an additional insulating layer for use when int resecting traces (e.g., crossovers) are not int nded to be inter-conductiv.

The invention may be further understood from the following more detailed description taken with the accompanying drawings.

BRIEF DESCRIPTION OF THE DRAWING

Figure 1 is an exploded side perspective view of a preferred embodiment of the membrane switch circuit layout.

Figure 2 is a side perspective view of a preferred embodiment of the membrane switch circuit layout.

Figure 3 is a top perspective view of a preferred embodiment of the membrane switch circuit layout.

DETAILED DESCRIPTION

It will be understood that the drawings are intended to teach a preferred embodiment of the present invention but are not intended to limit the invention thereto.

Referring now to Figures 1 and 2, there is depicted a side view a membrane switch circuit layout. Figure 1 particularly shows an exploded view of the layers of the membrane switch circuit layout. First and second membrane layers 10 and 12 respectively comprise the main structure of the circuit. The membrane layers 10 and 12 are 0.001 – 0.007 inches thick in a preferred embodiment. However, any thickness suitable to support conductive ink traces and provide insulation and/or thru-holes there between may be used.

The first membrane layer 10 is the support layer for the circuit. A circuit path 14 is printed on the first membrane layer 10. The circuit path may be printed with suitable conductive ink as is known in the art. An adhesive 16 is positioned over first membrane layer 10. As shown in this embodiment, the adhesive 16 may be an adhesiv layer selectively cut for openings. The adhesive 16 may be a pressure sensitive adhesive or